

S rial No.:09/523,990

Art Unit 2876

1 3. (Amended) The method of claim 1 wherein the non-black, optically transmissive material is [used  
2 for] adapted to provide protection from damage as the result of environmental [protection] and  
3 handling factors [of the silicon devices].

1 6. (Amended) The method of claim 1 wherein the non-black, optically transmissive material  
2 prevents remarking indicia or identification marks on the chip [device].

1 9. (Amended) A method of marking an electronic integrated circuit chip having surfaces  
2 comprising the following steps:

3 forming a semiconductor, integrated circuit chip having surfaces including a planar front  
4 surface, a planar back surface and edges of the chip between the planar surfaces with at least one  
5 electrical contact site on [on] a surface,

6 forming internal marking indicia upon an exterior marking portion of a surface of the chip  
7 for identification of the chip, and

8 forming a non-black layer covering the exterior surface of the chip at least at the exterior  
9 marking portion thereof, the non-black layer being composed, of a colored, optically transmissive  
10 material, which non-black layer cannot be scraped off of the chip for preventing replacement of the  
11 internal marking indicia by different markings and for preventing remarking the internal indicia on  
12 the exterior marking surface of the chip,

13 whereby the indicia are visible through the non-black layer.

Cancel claim 11.

1 12. (Amended) A method of marking a chip having surfaces comprising:

2 forming internal marking indicia on a marking location upon an exterior surface of the chip,  
3 and

4 forming a non-black, optically transparent material colored with a particular color over at  
5 least the marking location on that exterior surface of the chip wherein the material colored with the  
6 particular color together with the marking indicia represents identification of the chip which  
7 non-black, optically transparent, colored material cannot be scraped off of the chip for prevention of

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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**  
**IN THE SPECIFICATION**

Please amend the paragraph beginning at page 3, line 16 to read as follows:

- -An object is to provide internal colored markings and/or indicia on packages which cannot be [be] scraped off and replaced by different markings and/or indicia for purposes of relabeling or to cover up the original source of a product in cases of misappropriation of products. - -

Please amend the paragraph beginning at page 12 line 12 to read as follows:

FIG. 33 shows an alternative type of marking in accordance with this invention. In this case the difference is that the package P2 comprising a flip-chip (face down) CH3 has internal marking [indicia] indicia IM formed on the bottom surface (that is the active device surface) thereof. In this case the internal marking [indicia] indicia IM are protected from damage or remarking since chip CH3 is covered, at least in part, by a non-black, protection layer PL3 between elements of the BGA balls BL. Protection layer PL3 is formed directly on the lower surface (as seen in FIG. 33) of the flip-chip CH3 and on top of the internal marking indicia IM. Some chips are sensitive to light. This embodiment protects the light sensitive surface of the flip-chip CH3 from exposure to light leakage since the uncovered surface is facing the lower packaging element (not shown) which will protect the light sensitive surface of flip-chip CH3 from light

**IN THE CLAIMS**

Please amend the claims to read as follows:

1. (Amended) A method of marking a chip having surfaces comprising the following steps:
  - forming internal marking indicia on a marking location upon an exterior surface
  - of the chip for identification of the chip, and
  - forming a non-black, optically transmissive material over at least the marking location on the
  - one exterior surface of the chip which non-black, optically transmissive material cannot be scraped
  - off of the chip for prevention of replacement of the internal marking indicia by different markings.

8 replacement of the internal marking indicia by different markings.

1 13. (Amended) A chip comprising:

2 the chip having exterior surfaces,

3 internal marking indicia formed on a marking location upon an exterior surface of the chip  
4 for identification of the chip, and

5 a non-black, optically transmissive material formed over at least the marking location on the  
6 one exterior surface of the chip which non-black, optically transmissive material cannot be scraped  
7 off for prevention of replacement of the internal marking indicia by different markings.

1 14. (Amended) The chip [device] of claim 13 wherein the non-black, optically transmissive  
2 material comprises a non-black, transparent or semi-transparent material.

1 15. (Amended) The chip [device] of claim 13 wherein the non-black, optically transmissive  
2 material comprises a colored material.

1 16. (Amended) The chip [device] of claim 13 wherein the non-black, optically transmissive  
2 material prevents remarking indicia or identification marks on the chip [device].

1 17. (Amended) The chip [device] of claim 13 wherein the non-black, optically transmissive  
2 material prevents remarking silicon for a semiconductor package and the optically transmissive  
3 material is a transparent material.

1 18. (Amended) The chip [device] of claim 13 wherein:

2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the non-black optically transmissive material and

4 reading means are provided for reading the internal marking indicia in response to images of  
5 the internal marking indicia provided by reflections of the electromagnetic radiation.

1 19. (Amended) The chip [device] of claim 13 wherein the non-black, optically transmissive  
2 material ~~[is used for]~~ is adapted to provide protection from damage as the result of  
3 environmental ~~[protection]~~ and handling factors ~~[of the silicon devices]~~.

1 20. (Amended) The chip [device] of claim 14 wherein:

2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the non-black optically transmissive material and

4 reading means are provided for reading the internal marking indicia in response to images of  
5 the internal marking indicia provided by reflections of the electromagnetic radiation.

1 21. (Amended) The chip [device] of claim 17 wherein:

2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the non-black optically transmissive material and

4 reading means are provided for reading the internal marking indicia in response to images of  
5 the internal marking indicia provided by reflections of the electromagnetic radiation.

1 22. (Amended) An electronic integrated circuit chip comprising:

2 a semiconductor, integrated circuit chip having surfaces including a planar front surface, a  
3 planar back surface and edges of the chip between the planar surfaces with at least one electrical  
4 contact site on a surface,

5 indicia marked upon an exterior marking portion of a surface of the chip for identification of  
6 the chip,

7 a non-black layer covering the exterior surface of the chip at least at the exterior marking  
8 portion thereof, the non-black layer being composed,

9 ~~of a colored, optically transmissive material~~ which non-black, optically transmissive material cannot  
10 be scraped off of the chip for prevention of replacement of the indicia by different markings and for

11 preventing remarking the indicia on the exterior marking surface of the chip, and

12 the indicia being visible through the non-black layer.

1 23. (Amended) The chip [~~device~~] of claim 22 wherein:

2 illumination means are provided for directing electromagnetic radiation upon the internal  
3 marking indicia through the non-black optically transmissive material and

4 reading means are provided for reading the internal marking indicia in response to images of  
5 the internal marking indicia provided by reflections of the electromagnetic radiation.

Cancel claim 24.

1 25. (Amended) A chip comprising:

2 internal marking indicia formed on a marking location upon an exterior surface of the chip,  
3 and

4 a non-black, optically transparent material colored with a particular color formed over at  
5 least the marking location on that exterior surface of the chip

6 wherein the material colored with the particular color together with the marking indicia represents  
7 identification of the chip which non-black, optically transmissive material cannot be scraped off of  
8 the chip for prevention of replacement of the internal marking indicia by different markings.